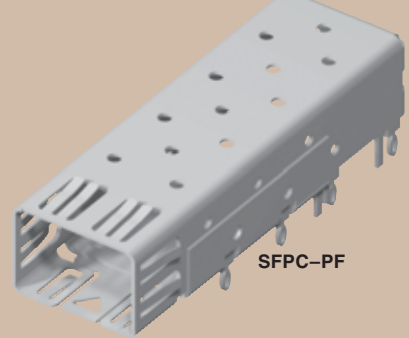




MECT-110-01-M-D-RA1



SFPC-PF

TRANSCEIVER INTERFACES

MECT, SFPC, SFPK SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MECT

- Insulator Material:** Black LCP
- Contact Material:** Phosphor Bronze
- Plating:** Sn or Au over 100µ" (2,54µm) Ni
- Operating Temp Range:** -55°C to +125°C
- Voltage Rating:** 265 VAC
- RoHS Compliant:** Yes
- Processing:**
 - Max Processing Temp:** 230°C for 60 seconds, or 260°C for 20 seconds 3x
 - Lead-Free Solderable:** Yes
 - SMT Lead Coplanarity:** (0,10mm) .004" max (10-35)



Note: Some sizes, styles and options are non-standard, non-returnable.

MECT	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	D	RA1	OTHER OPTION
		10, 15, 35	-01 = (1mm) .039" thick board	-M = 15µ" (0,38µm) Gold on contact, Matte Tin on tail			-TR = Tape & Reel Packaging

Mates with: SFP, XFP or XENPAK transceivers (For MSA specifications see www.schelto.com)

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SFPC

For SFP specifications see www.schelto.com/SFP

TYPE	TERMINATION	CONNECTOR PACKAGE
Use with: MECT	-PF = Press Fit	SFPK only
SFPC = Cage	-SL = Solder Lead	-TR = Tape & Reel (Leave blank for tube packaging)
SFPK = Cage and Connector Kit (SFPC & MECT-110-01-M-D-RA1)	-PC = PCI Press Fit (1% slope for PCI specifications)	

APPLICATION

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM